

Annual meeting,
18-19 October 2022

JRA9-Tracking and Ions Identifications with Minimal Material budget: TIIMM

This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 824093

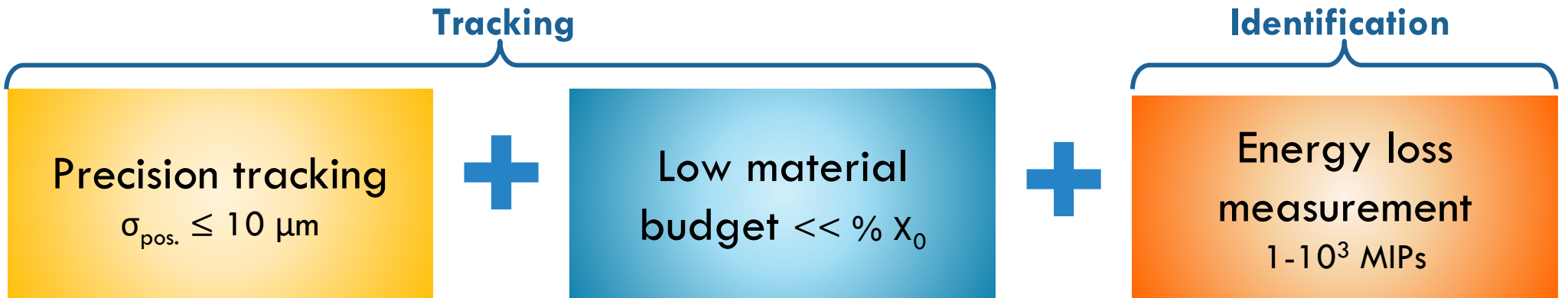


PLAN OF PRESENTATION

- 1) Scientific results obtained since the last year
- 2) Modifications of the scientific Work Plan
(as compared to the initial plan in the Grant Agreement)
- 3) Possibilities/needs of another request for the extension of the project (beyond 30 November 2023)

CONTEXT

TIIMM target =



Current achievements

Hybrid detectors

- At the limit of feasibility

- Limit around 1 % X_0

- **Strong point**
 - Thick substrate 300-1000 μm

Monolithic sensors

- **~5 μm** ALICE – ITS2
 - with 1-10 MIPs
- **5-10 μm** FIRST, hadrontherapy
 - Ions 150-300 MeV/u

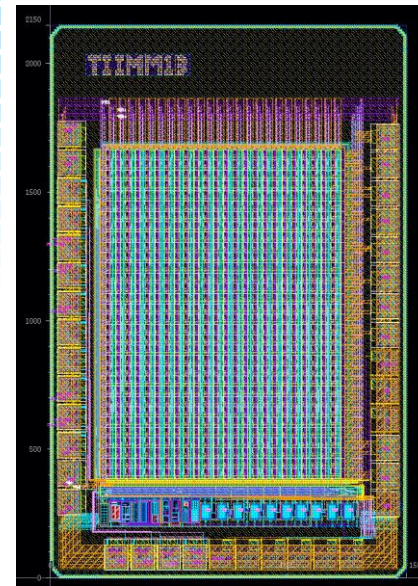
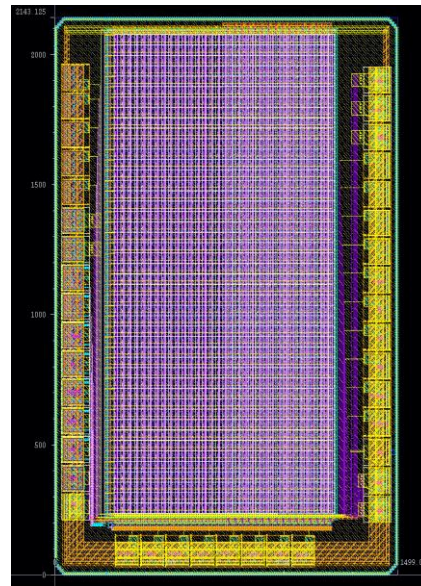
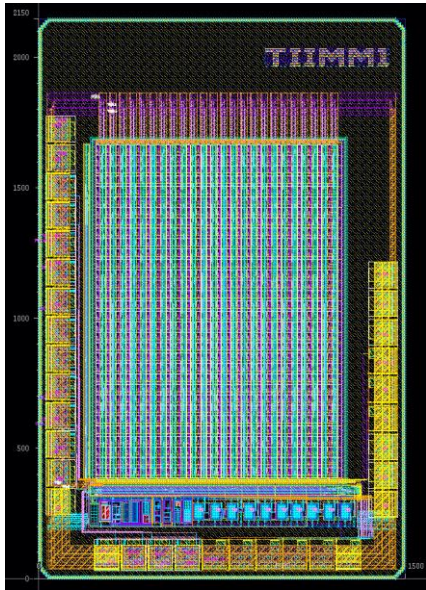
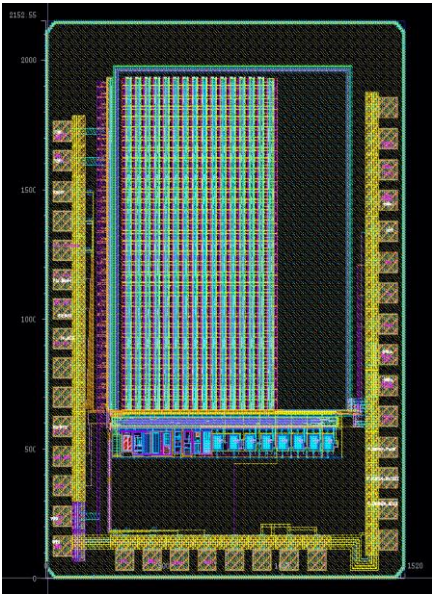
- **0.3 to 0.8 % X_0**
 - ALICE – ITS2 over 10 m^2
- **~0.2 % X_0**
 - FOOT prototype over 30 cm^2

- Available for MIP level
 - σ_E not investigated
- Initial work for \gg MIPs
- Indirect estimation of ΔE

SENSOR'S OVERVIEW

CMOS Monolithic Active Pixel Sensor design in TowerJazz 180 nm process
For position and energy measurements

- **First submission: preliminary prototype (TIIMM0) submitted in March 2020.**
- **Second submission: TIIMM0/TIIMM1/TIIMM1A/TIIMM1B prototypes received in August 2022**



7 sensing layer variants

Thickness	Process	
25 μm Epi High Res.	Standar	1. Non-uniform N- layer 2. Uniform N- layer + Extra Deep
50 μm Epi High Res.		1. Non-uniform N- layer 2. Uniform N- layer + Extra Deep P
100 μm Epi High Res.		1. Non-uniform N- layer 2. Uniform N- layer + Extra Deep P

TIIMM0 (second submission)
 Chip area: 2.2 mm * 1.5 mm
 Matrix: 32 (rows) * 16 (col)
 Pixel pitch: 40 μm × 40 μm

TIIMM1 sensor
 Chip area: 2.2 mm * 1.5 mm
 Matrix: 32 (rows) * 24 (col)
 Pixel pitch: 41.2 μm × 40 μm

TIIMM1A sensor
 Chip area: 2.2 mm * 1.5 mm
 Matrix: 46 (rows) * 32 (col)

TIIMM1B sensor
 Chip area: 2.2 mm * 1.5 mm
 Matrix: 32 (rows) * 24 (col)
 Pixel pitch: 41.2 μm × 40 μm

Corrected from the first submission

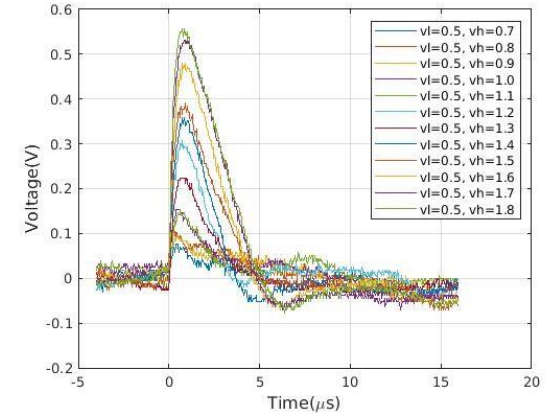
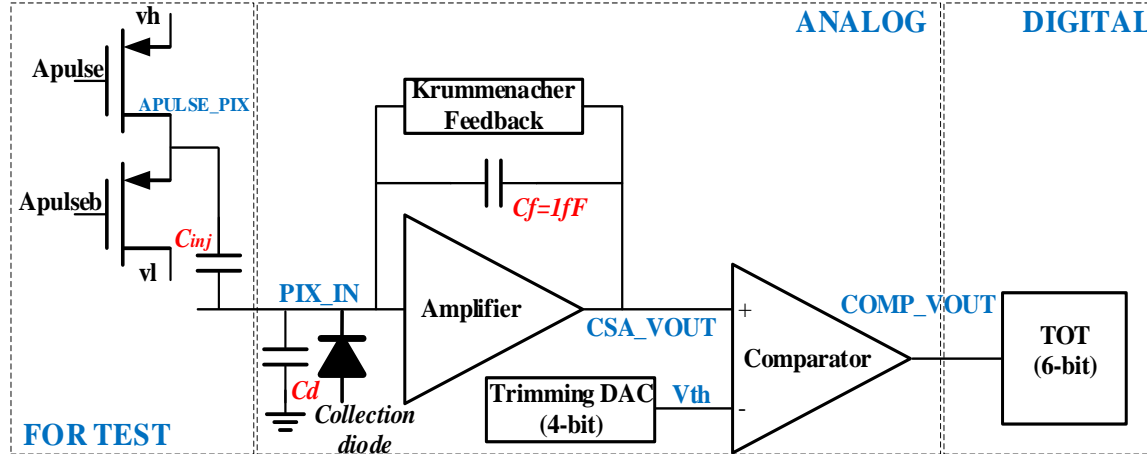
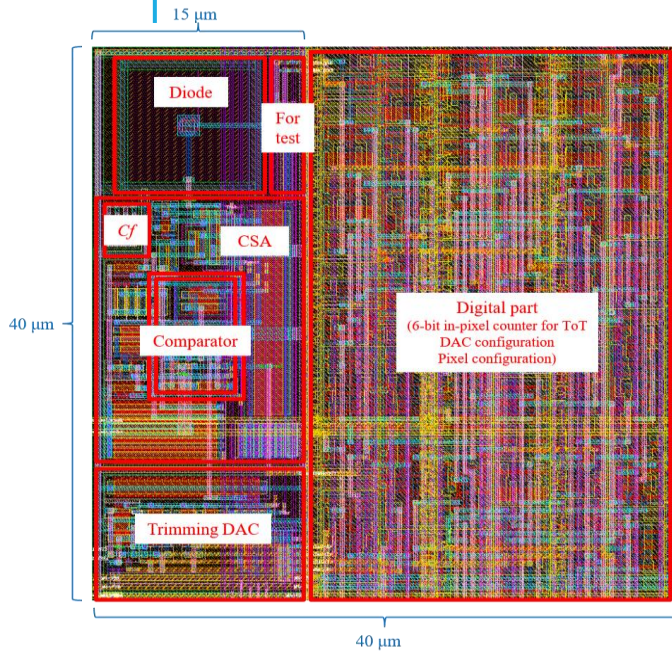
New front-end

New front end
 Analog part study only

New front-end enhanced

SENSOR'S OVERVIEW – TIIMMO (FIRST SUBMISSION)

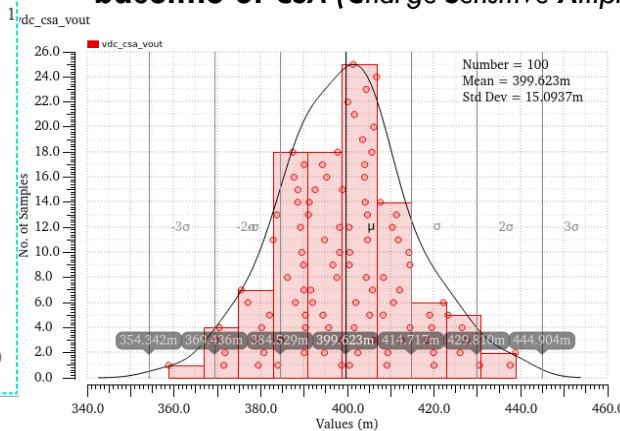
Measurements



CSA analogue output's / different input charge.

Simulations

Monte Carlo simulation of voltage baseline of CSA (Charge Sensitive Amplifier) output



Limitations in TIIMMO (simulations):

1. Maximum linear range is only 110ke-
2. The baseline spread of the Charge Sensitive Amplifier (CSA) output is large.
3. The dispersion of the pulse width of the CSA output is large
4. Undershoot problem in CSA output

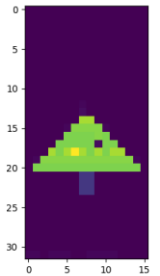
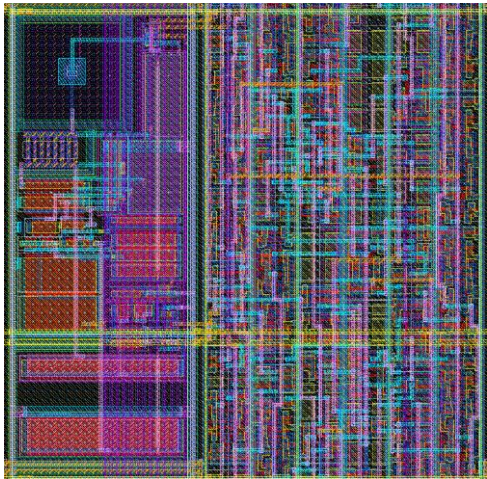
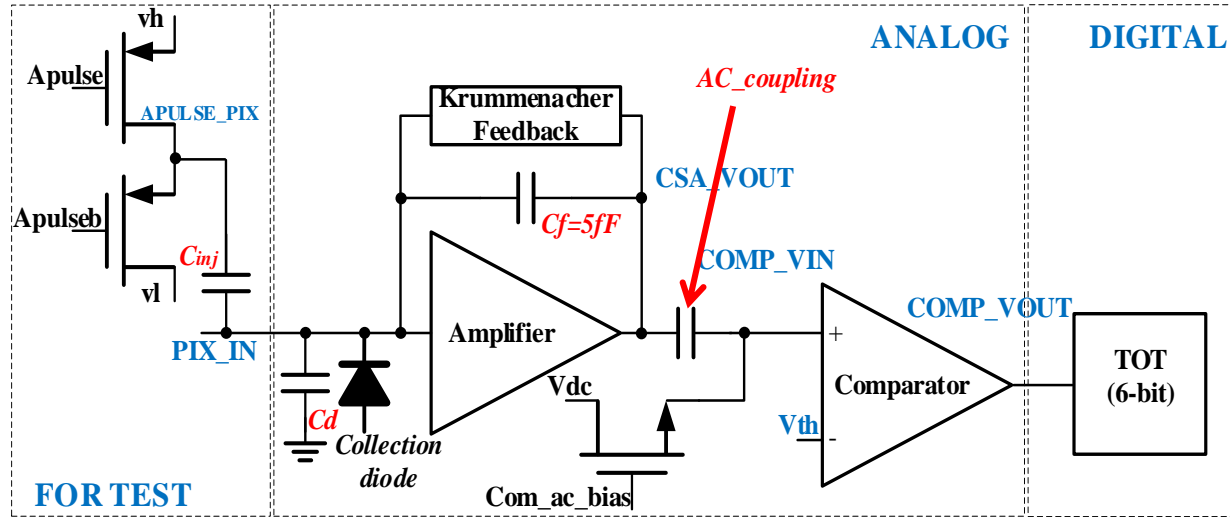


Image with digital readout test

SENSOR'S OVERVIEW – TIIMM1 (SECOND SUBMISSION – SIMULATION ONLY)



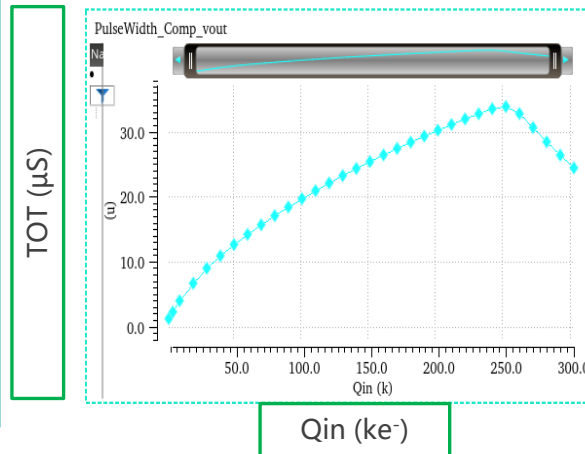
TIIMM1 pixel cell $40\ \mu\text{m} \times 41.2\ \mu\text{m}$



■ Spread of input comparator in TIIMM0
Mean: 400.22 mV
Sigma: 15.1 mV

■ Spread of input comparator in TIIMM1
Mean: 400 mV
Sigma: 1.11 μV

TOT: Time Over Threshold



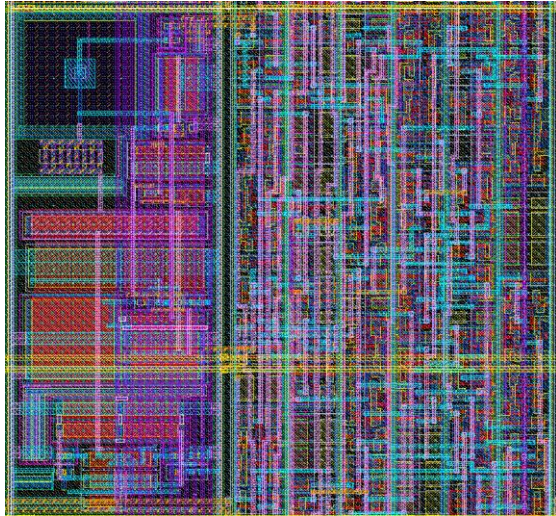
Limitations in TIIMM1:

1. Input dynamic range is greater than TIIMM0 but still limited to 250ke^- ($<10^3$ MIPs)
2. undershoot problem in CSA output
3. The input offset (*mismatch and process*) of the comparator is still large (6mV).

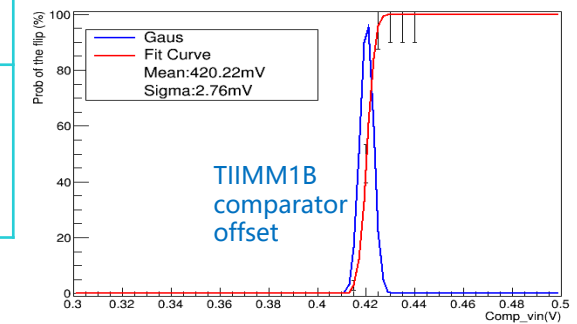
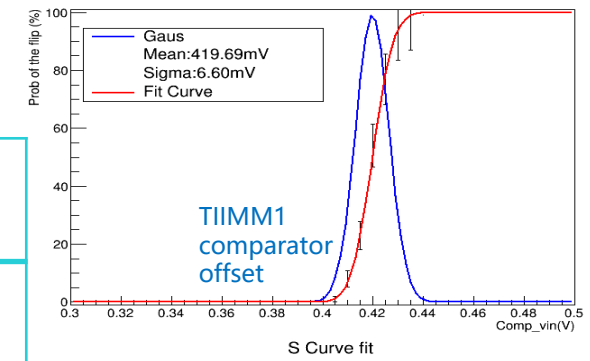
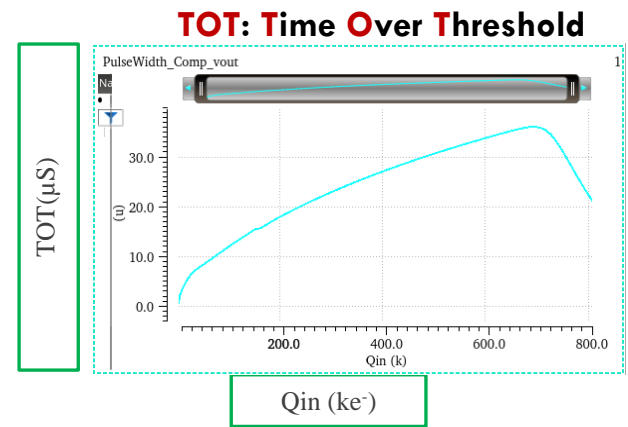
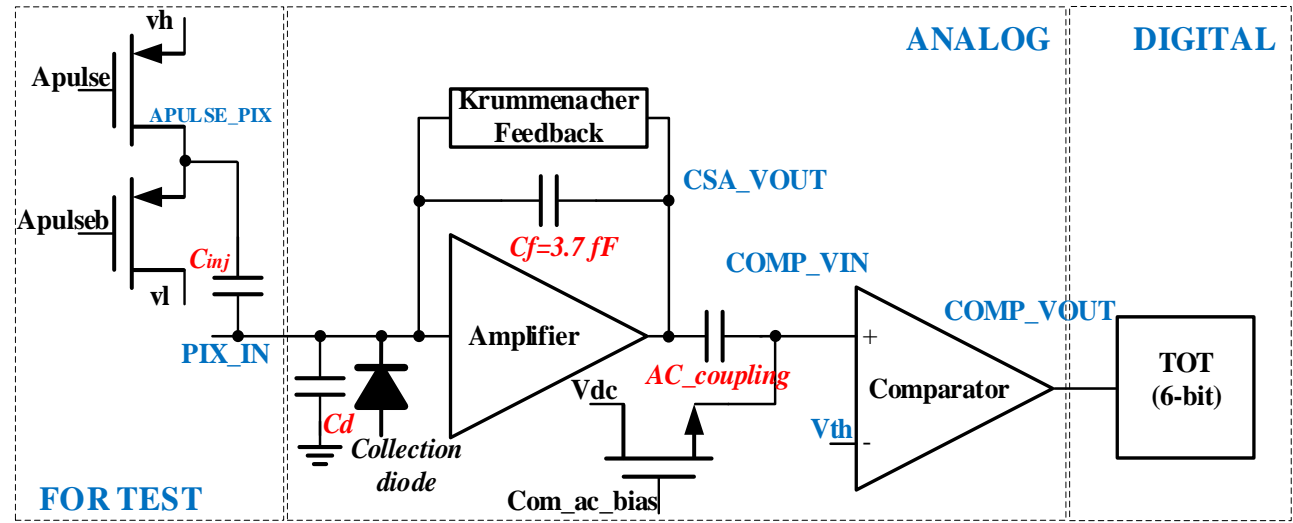
Optimization in TIIMM1:

1. Increase the C_f to have larger dynamic range.
2. AC coupling structure to fix the offset problem of the CSA output.
3. Optimization of the CSA to minimize dispersion of the pulse width.
4. Keep the digital readout structure.

SENSOR'S OVERVIEW – TIIMM1B (SECOND SUBMISSION – SIMULATIONS ONLY)



TIIMM1B pixel cell



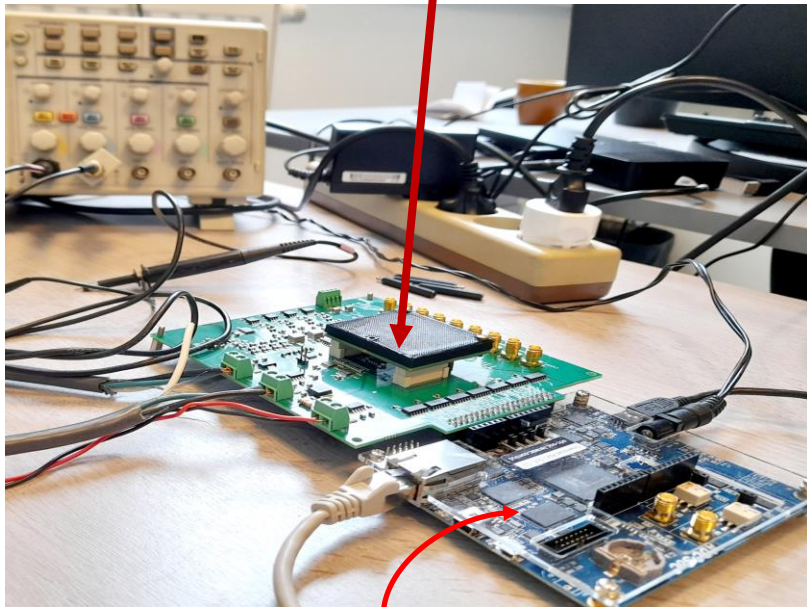
TIIMM1 vs TIIMM1B

- ❑ Amplifier structure optimized for larger input dynamic range
- ❑ New Comparator structure with less intrinsic input offset

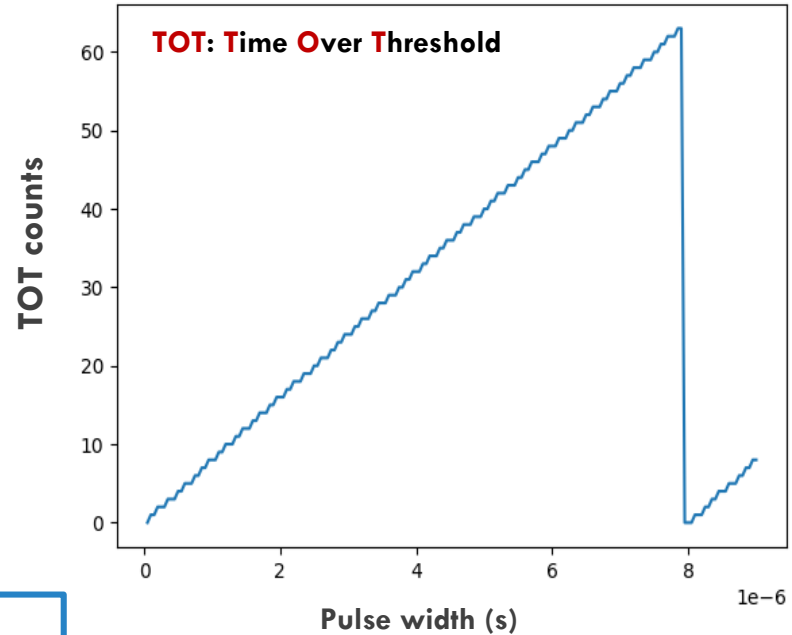
	TIIMM1	TIIMM1B
Range of TOT	Maximum at 250ke ⁻	Maximum at 700ke ⁻
Comparator input offset	6.6 mV	2.7 mV

TIIMM1B – First Functional test results (single pixel)

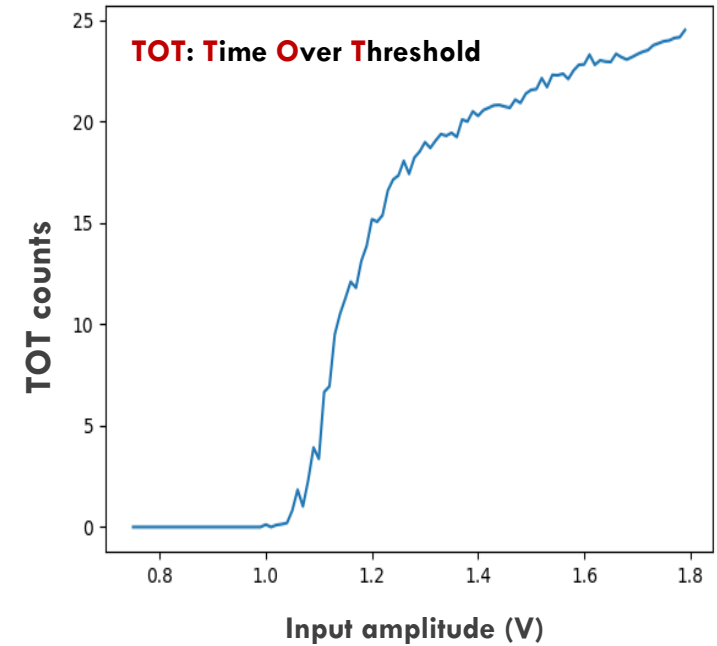
TIIMM1B Sensor covered



Digital part



Full chain



Setup:

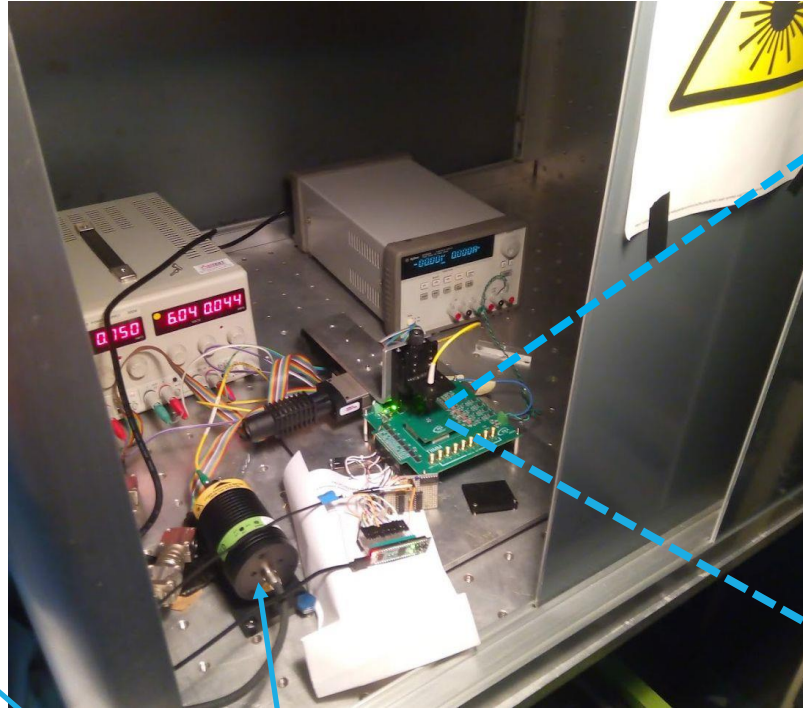
1. **ADC – SOC** (FPGA: Cyclone V with ARM- A9 running Linux)
2. **Automatic controlled Pulses generator**
3. **Sensor prototype wire bonded on custom board**
4. **monitoring ADC, biasing DACs, analog outputs readout**
5. **Full control acquisition system**

- External digital pulse generator (hits emulator)
- TOT counting is correct (6bits)

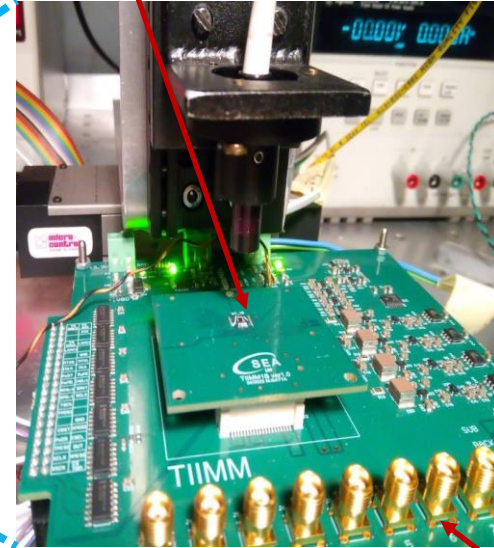
- Internal analog injection pulse (using parasitic capacitor)
- The full chain working

TIIMM1B – FIRST LASER TESTS

Single pixel CSA output signal with 2 laser pulses



TIIMM1B sensor



- We can move the laser spot in x/y direction with 1µm step precision
- We are able to inject charge in a single pixel
- Positioning and number of laser pulses are remotely controlled

Pulsed Diode LASER
(Model LDH-P-C-N-1060)

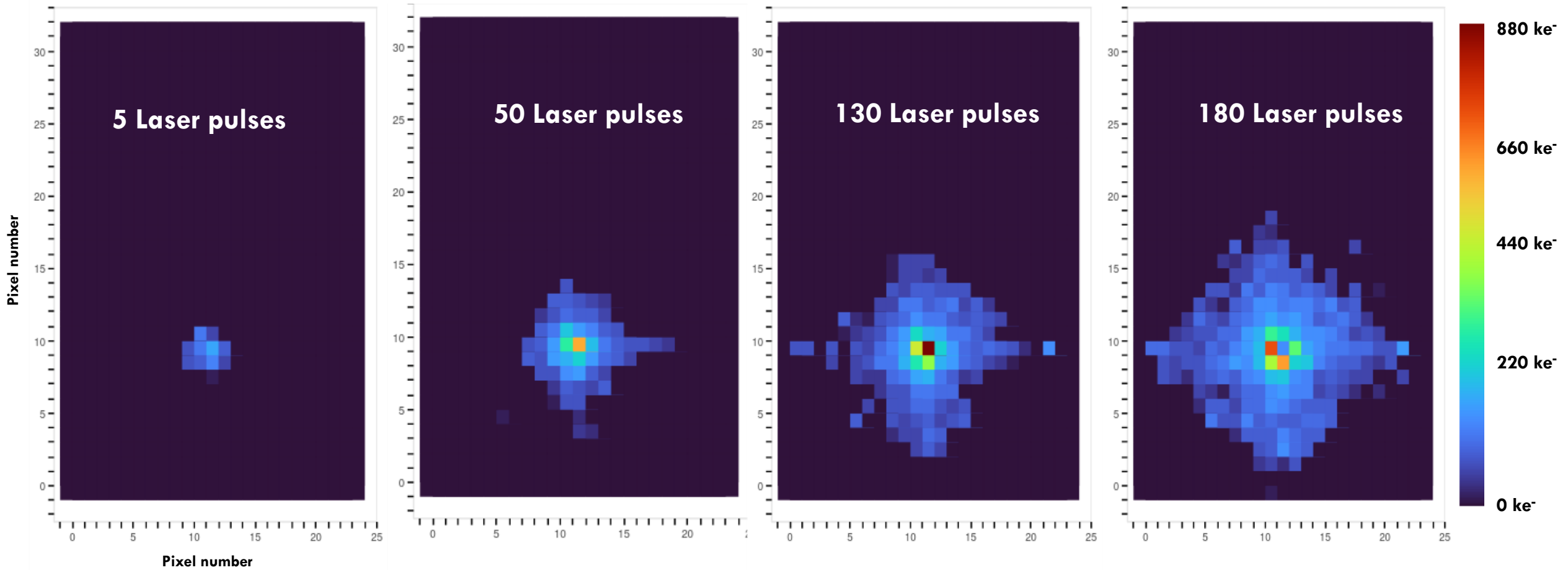
- Selectable repetition frequencies: 3.25 KHz to 80 MHz
- Wavelength (average): 1061 nm
- Peak power (intensity): from 18 mW to 400 mW
- FWHM (time-width): 88 ps to 500 ps

Pulse generator
(Model HP 811A)

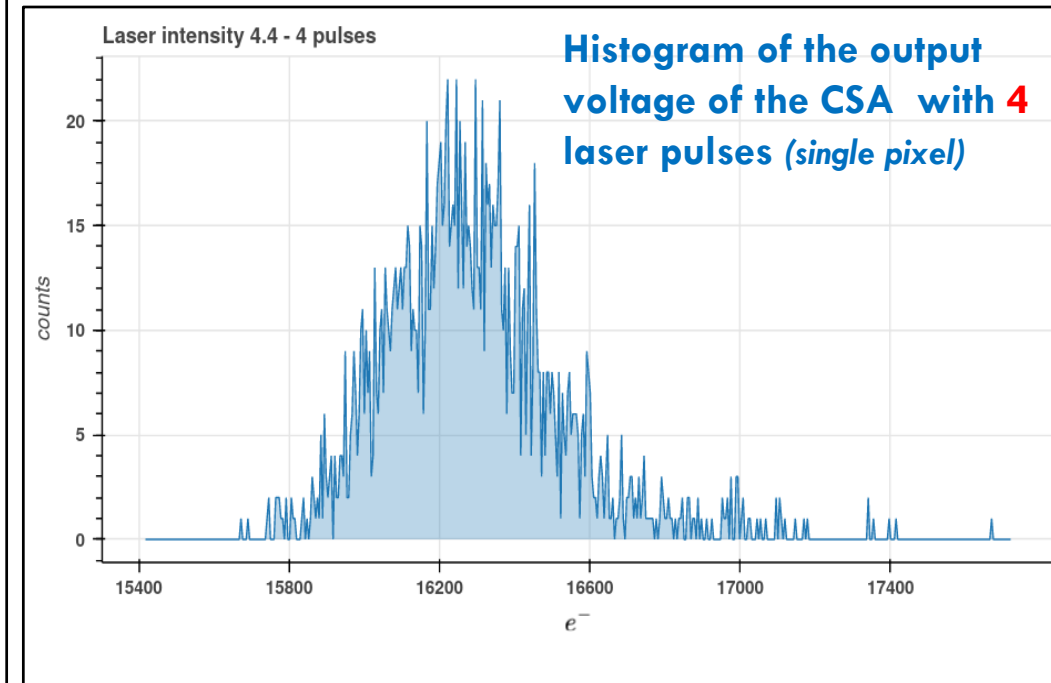
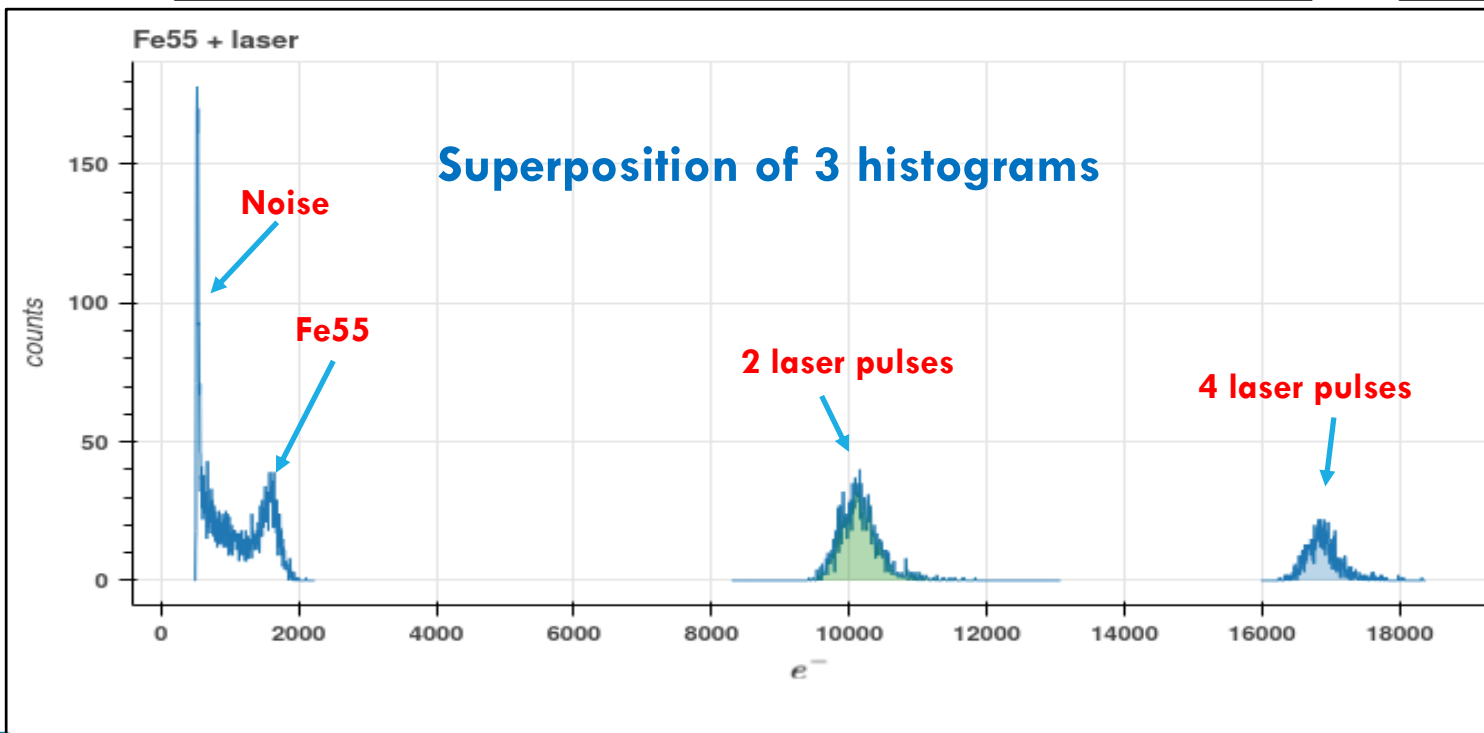
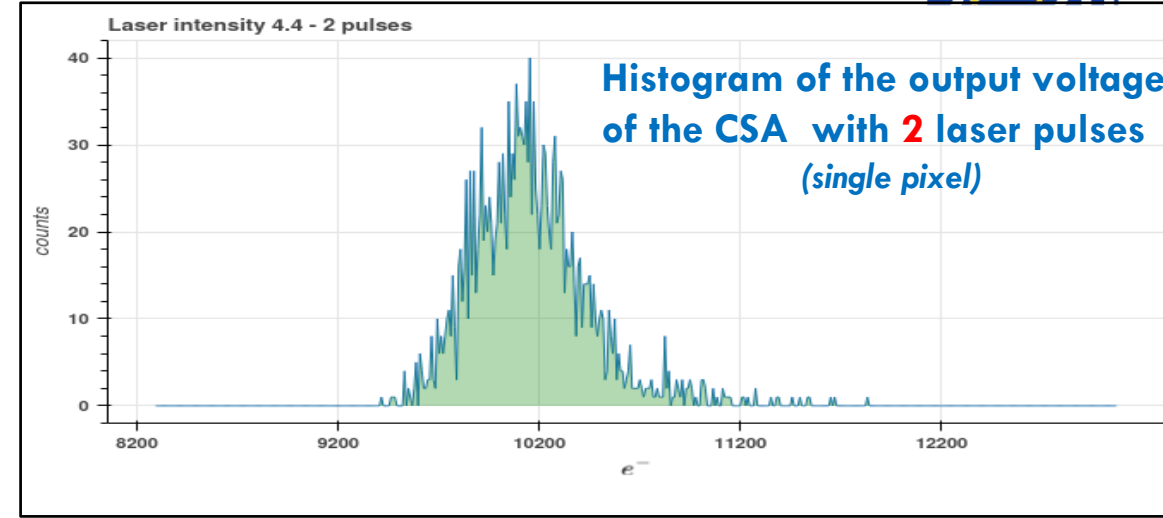
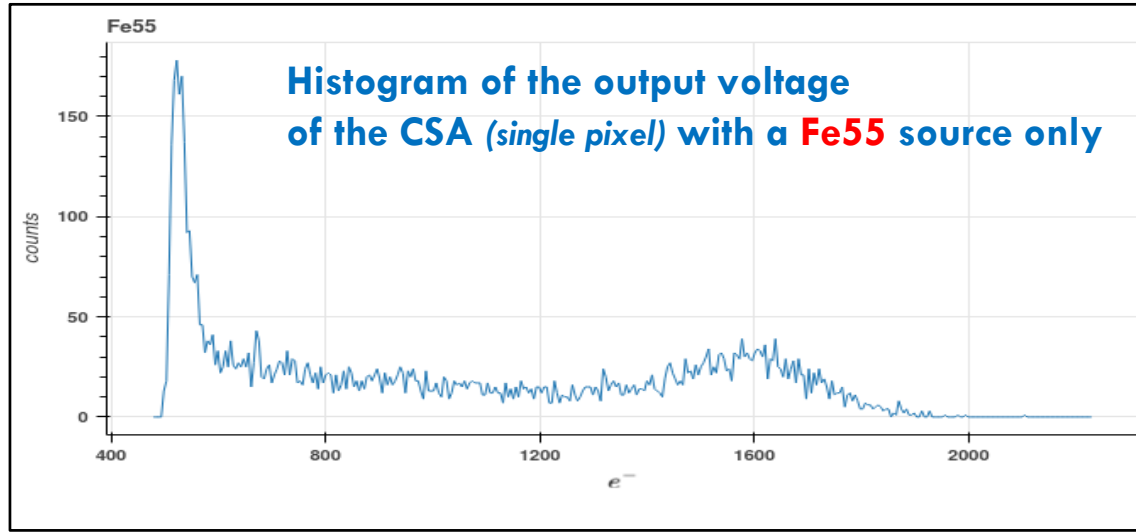
- Width: 5 ns ; Period: 10 ns
- Amp: 2 V
- Leading-edge: 2ns ; Trailing-edge: 2ns

8 analog outputs to perform different measurements with the oscilloscope

TIIMM1B – FIRST LASER TESTS - FULL MATRIX HEAT MAP

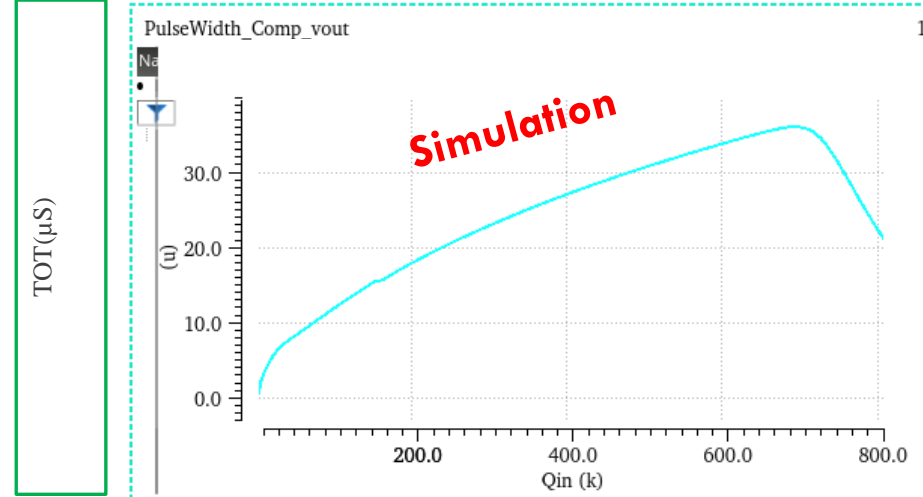
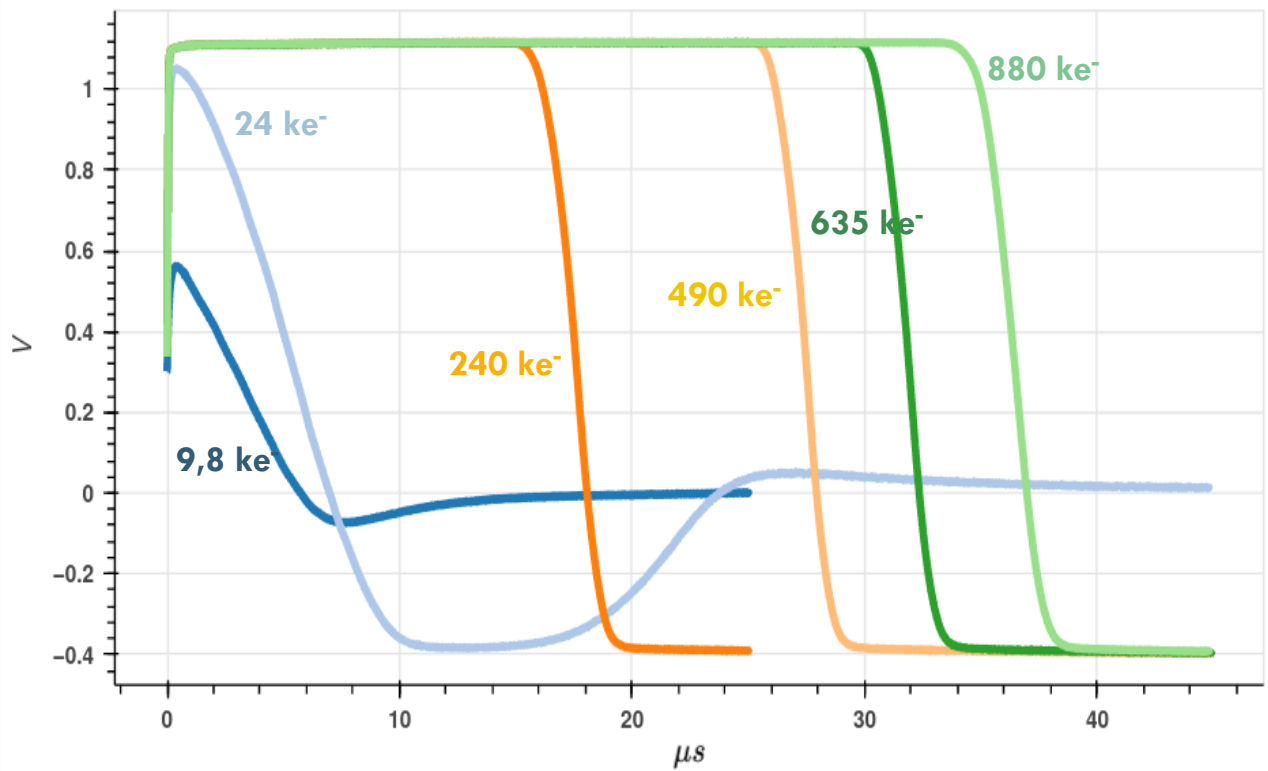


TIIMM1B – CSA output preliminary tests with Fe55 source - Calibration



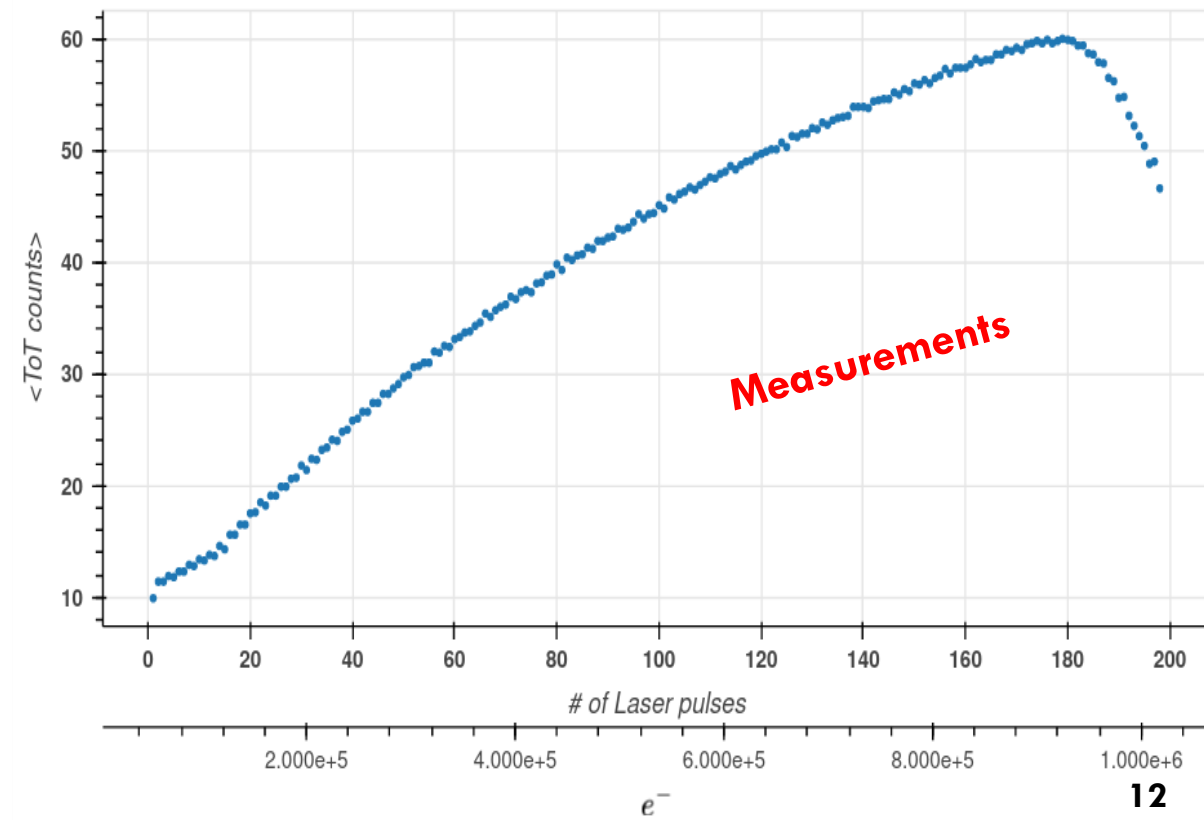
TIIMM1B – FIRST LASER TESTS ENERGY LOSS MEASUREMENT (SINGLE PIXEL TOT)

Charge Sensitive Amplifier output voltage (oscilloscope)



Qin (ke⁻)

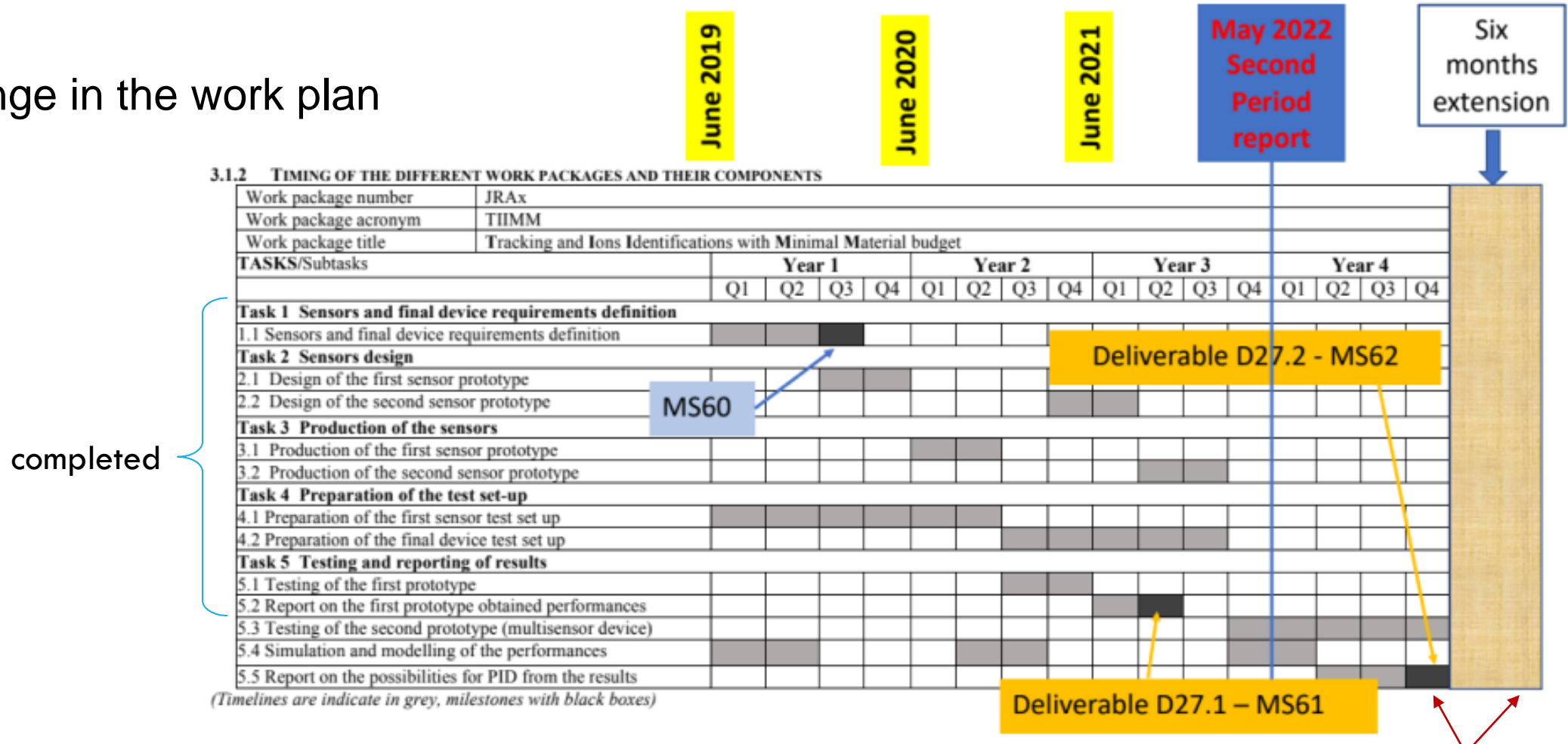
TIIMM1B ToT under Laser beam



Range of measured charges on single pixel: ~ [500e⁻ , 900Ke⁻]

STATUS ON THE WORK PLAN

No change in the work plan



completed

Tests might not be fully completed by May 2023 but OK for Nov. 2023

CONCLUSIONS & EXTENSION BEYOND NOVEMBER 2023

Current results of second prototypes are very promising

- Continue in-lab test
- Beam tests with ions planned in first half of 2023

Possibility to extend the scope of our WP

- Combine the pixel front-end developed within TIIMM with a **faster** scalable matrix digital read-out
- Third prototype, still small area ($\sim 5 \times 5 \text{ mm}^2$), but otherwise almost complete sensor / usage in experiment

Schedule

- Third prototype design can be achieved within current project but not with delivery and tests.
- Fabrication and Tests would require an additional 6-12 months

THANKS

Backup

